

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3295345

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KENG-YU CHOU	03/19/2015
CHUN-HAO CHUANG	03/19/2015
CHIEN-HSIEN TSENG	03/19/2015
SHYH-FANN TING	03/26/2015
WEI-CHIEH CHIANG	03/19/2015
YUICHIRO YAMASHITA	03/19/2015
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14663899
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	216-502-0600
Email:	docketing@eschweilerlaw.com
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.
Address Line 1:	629 EUCLID AVENUE, SUITE 1000
Address Line 2:	NATIONAL CITY BANK BUILDING
Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP544US
NAME OF SUBMITTER:	DAVID W. POTASHNIK
SIGNATURE:	/David W. Potashnik/
DATE SIGNED:	04/02/2015

PATENT

Total Attachments: 8

source=Assignment#page1.tif

source=Assignment#page2.tif

source=Assignment#page3.tif

source=Assignment#page4.tif

source=Assignment#page5.tif

source=Assignment#page6.tif

source=Assignment#page7.tif

source=Assignment#page8.tif

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Keng-Yu Chou
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Chun-Hao Chuang
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Chien-Hsien Tseng
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Shyh-Fann Ting
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Wei-Chieh Chiang
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Yuichiro Yamashita
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
**"A COMPOSITE GRID STRUCTURE TO REDUCE CROSSTALK IN BACK SIDE
ILLUMINATION IMAGE SENSORS"** for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or

was filed on _____ and accorded U.S. Serial No. _____; or

I hereby authorize and request my attorney associated with Customer No.
107476, to insert on the designated lines below the filing date and application
number of said application when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is
desirous of acquiring the entire right, title and interest in and to the invention and in and to
any letters patent that may be granted therefore in the United States and in any and all
foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of
which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto
ASSIGNEE its successors and assigns, the entire right, title and interest in and to said
invention and improvements, said application and any and all letters patent which may be
granted for said invention in the United States of America and its territorial possessions and
in any and all foreign countries, and in any and all divisions, reissues, re-examinations and
continuations thereof, including the right to file foreign applications directly in the name of
ASSIGNEE and to claim priority rights deriving from said United States application to which

said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2015. 3. 19
Date

Keng - Yu Chou
Name 1st Inventor Keng-Yu Chou

TSMC Docket No. P20150026US00
Docket No. TSMCP544US

2015. 3. 19
Date

Chun-Hao Chuang.
Name 2nd Inventor Chun-Hao Chuang

TSMC Docket No. P20150026US00
Docket No. TSMCP544US

3/19/2015
Date

Chien-Hsien Tseng
Name 3rd Inventor Chien-Hsien Tseng

TSMC Docket No. P20150026US00
Docket No. TSMCP544US

2015.03.26
Date

Shyh-Fann Ting
Name 4th Inventor Shyh-Fann Ting

TSMC Docket No. P20150026US00
Docket No. TSMCP544US

3/19/2015
Date

wei-chieh chiang
Name 5th Inventor Wei-Chieh Chiang

2015/3/19
Date

Yuichiro Yamashita
Name 6th Inventor Yuichiro Yamashita